



MATERIALS FOR POWER STORAGE SYSTEMS

ELECTRIC AND HYBRID VEHICLE SOLUTIONS





CONTENTS

itroduction3

Multiple Levels of Battery Solutions

Battery Cells	4
Battery Modules	.5
Battery Packs	.5

Materials for Lithium Ion Batteries

Bonding Materials	
Connecting Materials	
Protecting Materials	
Thermal Materials	



INTRODUCTION Electric and Hybrid Vehicles Charging Ahead

Henkel's comprehensive portfolio of materials for electric and hybrid vehicles and power storage systems is driving unprecedented levels of performance, efficiency, reliability and safety.

Our latest automotive electronic material innovations facilitate the manufacture of high-energy density, lightweight Lithium-Ion (Li-Ion) batteries and their related sub-systems, which are key to enabling the longer ranges and speed expectations of today's plug-in hybrid electric and electric vehicles. Henkel's bonding, connecting, protecting and thermal formulations deliver advantages at the individual cell level all the way through to the battery pack, power conversion systems and control units.

Performance Enablers

Beneath the cool, quiet exterior of modern electric vehicles are powerful Li-Ion battery packs working in concert to facilitate the entire driving experience. Within each pack are a series of modules, which house the individual battery cells. At every level of the battery structure – and even outside the battery in the power inverter and engine control unit (ECU) – Henkel electronic materials are accelerating efficiency, reliability, battery life and, ultimately, safety. Bonding materials secure housings and lead frames for rugged conditions, while high-performance solders, adhesives and inks deliver reliable and responsive interconnects. Between each of the battery components, award-winning BERGQUIST brand thermal management materials are dissipating the heat generated by charging and discharging these workhorses. Safeguarding the entire battery system from top to bottom are Henkel protection materials to defend against exposure to fluids, harsh conditions, vibration and thermal shock.

MULTIPLE LEVELS OF BATTERY SOLUTIONS

Battery Cells

At the cell level, Henkel's functional coatings pre-treat anodes and cathodes for better conductivity, while unique PTC inks elevate cell temperature in freezing conditions for optimal performance and longer battery life.



• Cell Benefits

- Pre-treatment coating of anodes and cathodes enhances bonding for improved conductivity.
- Extend battery life and reduce weight with Henkel's novel battery heating PTC inks.
 Temperature is known to have a significant impact on battery performance, safety and cycle lifetime; Henkel's positive temperature coefficient (PTC) self-regulating printed inks provide a thin, light solution for heating in freezing conditions.

Cell	Level	Product	Portfol	io

Application	Technology	Cell Level
Bonding	Structural Adhesives	
Bollanis	Thread Locking Adhesives	
	Electrically Conductive Adhesives	
Connecting	Printed Inks	✓
	Solder Materials	
	Conformal Coatings	
	Encapsulants	
Ductostina	Functional Coatings	✓
Protecting	Low Pressure Molding	
	Sealants	
	Potting	
Thormal	Insulated Metal Substrate	
Inermai	Thermal Interface Materials	

Battery Modules

Multiple Henkel materials work in collaboration within the battery module for rugged, reliable and responsive function.

Module and Pack Benefits

- Protect sensitive components within the battery module through a simple, three-step solution.
 Low pressure molding can replace metal and plastic housings, circuit board protection, sealing and thermal management.
- Enable ruggedness and durability with robust structural adhesives and sealants.
- High-performance electrical function is enabled through award-winning electrically conductive adhesives and solder materials.
- Manage high power densities and extreme heat generation with BERGQUIST brand thermal interface materials in a range of formats and conductivities.



Battery Packs

Henkel innovations seal, protect, connect and cool multiple components in battery packs, providing drivers with on-demand power and on-the-road reliability.



Thermal Interface Material

Module Level Product Portfolio

A 1: 4:	To shu ala mu	Module Level				
Application	Technology	Battery Control Module	Module Housing & Assembly			
Dending	Structural Adhesives		\checkmark			
вопатив	Thread Locking Adhesives		\checkmark			
	Electrically Conductive Adhesives	\checkmark	\checkmark			
Connecting	Printed Inks		\checkmark			
	Solder Materials	\checkmark				
	Conformal Coatings	✓				
	Encapsulants	\checkmark				
Dests stin -	Functional Coatings					
Protecting	Low Pressure Molding		\checkmark			
	Sealants	\checkmark	\checkmark			
	Potting		\checkmark			
Thousal	Insulated Metal Substrate	✓				
Thermal	Thermal Interface Materials	\checkmark	\checkmark			

Pack Level Product Portfolio

Application	Technology	Pack Level				
Application	recimology	Master Control Module	Pack Housing & Assembly			
Dending	Structural Adhesives		\checkmark			
вопатив	Thread Locking Adhesives		\checkmark			
	Electrically Conductive Adhesives	\checkmark	\checkmark			
Connecting	Printed Inks					
	Solder Materials	\checkmark				
	Conformal Coatings	\checkmark				
	Encapsulants	\checkmark				
Ducto stin -	Functional Coatings					
Protecting	Low Pressure Molding	\checkmark	\checkmark			
	Sealants	\checkmark	\checkmark			
	Potting		\checkmark			
Thermol	Insulated Metal Substrate	\checkmark				
Thermal	Thermal Interface Materials	\checkmark	\checkmark			

Battery Packs (Continued): Electric Heating Systems



Pack Level Product Portfolio (Continued)

Application	Technology	Pack Level (Continued)
Аррисаціон	теспноюду	Electric Heating Systems
Dending	Structural Adhesives	<i>√</i>
Bonding	Thread Locking Adhesives	
	Electrically Conductive Adhesives	<i>√</i>
Connecting	Printed Inks	1
	Solder Materials	✓
	Conformal Coatings	✓
	Encapsulants	
Dura ta ati a -	Functional Coatings	
Protecting	Low Pressure Molding	
	Sealants	✓
	Potting	1
Thomas	Insulated Metal Substrate	
Inermal	Thermal Interface Materials	✓

Battery Packs (Continued): Coolant Pumps



Pack Level Product Portfolio (Continued)

A	The state of the second	Pack Level (Continued)
Application	тесппотоду	Coolant Pumps
	Structural Adhesives	
Bonaing	Thread Locking Adhesives	
	Electrically Conductive Adhesives	✓
Connecting	Printed Inks	
	Solder Materials	1
	Conformal Coatings	✓
	Encapsulants	✓
	Functional Coatings	
Protecting	Low Pressure Molding	
	Sealants	✓
	Potting	1
The sum of	Insulated Metal Substrate	✓
Inermal	Thermal Interface Materials	✓



MATERIALS FOR LITHIUM ION BATTERIES

Lasting Bonds

A strong, cohesive structure for all of the components of a battery pack is integral to long-term function and durability. Today's Li-Ion batteries must withstand tremendous in-use vibration and maintain structural integrity even within these conditions. As the global leader in adhesives development, Henkel's awardwinning LOCTITE formulations deliver uncompromising structural reliability for Li-Ion battery modules and battery packs. Within the module, rugged cell to cell and cell to module bonding are achieved with proven structural adhesives developed specifically for battery applications. These materials also ensure that the battery pack housing is securely attached and sealed, keeping fluids, dust and moisture out. LOCTITE brand adhesive strength is found in the battery's mechanically attached components as well. While screws and fasteners are designed to hold parts together, road vibration can loosen the threads and risk separation of copper lead frames or housings. LOCTITE thread locking adhesives eliminate this risk, securing mechanical parts for battery endurance.



* Product not available in Europe

STRUCTURAL ADHESIVES

Product Name	Description	Key Attributes	Color Viscosity (cP)		Cure Time	Operating Temperature (°C)	Fixture time
Room Temperature Cu	re						
LOCTITE H8000*	Two component, room temperature curing methacrylate adhesive system	 Superior impact and peel strength Little or no surface preparation Rapid room temperature cure Excellent environmental resistance 	rength ion re stance Part A: Yellow Part B: Blue Mix: Green Part B: 25°C: 160,000 – 250,000 Part B at 25°C: 20,000 – 50,000		24 hr. at 22 °C	-50°C – 120°C	25 – 30 min. at 25℃
LOCTITE H3500	Two component, room temperature curing methacrylate adhesive system	 High strength, durable bonds on various metals and plastics High impact strength and maintains strength over a wide temperature range 	Part A: White Part A: Part B: Yellow 29,000 Mix: Light Part B: Yellow 18,000		24 hr. at 22 °C	-50°C – 120°C	18 – 20 min. at 21°C
UV Cure							
LOCTITE AA 3525	One component, UV curing acrylic adhesive	 Fast cure Excellent flexibility, toughness and durability to moisture exposure when cured Bonds to glass, metals and plastics for industiral applications 	Clear, colorless bonds	ear, colorless 9,500 to 21,000 bonds at 25°C		-50°C – 120°C	Less than 5 sec. with black light, 6 mW/cm ²

* Product not available in Europe

THREAD LOCKING ADHESIVES

Moisture Cure

Product Name	Description	Key Attributes	Color	Viscosity at 25°C (cP)	Cure Time	Operating Temperature (°C)	Fixture Time at 25°C
Moisture Cure							
LOCTITE 4031	Cyanoacrylate thread locking adhesive	 One component Low odor for applications where vapor control is vital Low bloom for cosmetic applications Suitable for metals, plastics and elastomers 	Transparent, colorless to pale yellow	1,650	24 hr. at 22 °C	-50 – 70	5 – 180 sec. depending on substrate
LOCTITE 4601	Cyanoacrylate thread locking adhesive	 One component Low odor for applications where vapor control is vital Low bloom for cosmetic applications Suitable for metals, plastics and elastomers Low viscosity 	Transparent, colorless to pale yellow	30 - 60	24 hr. at 22 °C	-50 – 70	5 – 180 sec. depending on substrate





Strong Connections

Printed circuit boards (PCBs) within each Li-Ion battery module feed information about cell temperature, charging/discharging speed and overall module stress and performance to the master battery pack control module PCB, which manages battery pack operation. At the board level, Henkel's proven interconnect solutions deliver reliable and responsive electronic function to drive and monitor battery performance. Advanced materials such as high-reliability solder alloys, temperature stable LOCTITE solder pastes and electrically conductive adhesives provide superior interconnection of components to substrates. Connection versatility is further enhanced with Henkel's printed inks, which deliver electrical performance in space-constrained areas and also enable battery performance through printed temperature sensors for use in heating applications.



COMPONENT ASSEMBLY MATERIALS

Electrically Conductive Adhesives

Product Name	Description	Key Attributes	Volume Resistivity	Glass Transition Temperature	Coefficient of Thermal Expansion (CTE)		Modulus at 25 °C	Recommended Cure
			(Ω•cm)	Tg (°C)	Below T _g	Above T _g	(MPa)	cure
Ероху								
LOCTITE ABLESTIK 2902	Epoxy electrically conductive adhesive	 Two component, solvent-free Room temperature cure Good adhesion to variety of substrates 	0.0006	52	49	N/A	N/A	24 hr. at 25°C or 1 – 4 hr. at 65°C
LOCTITE ABLESTIK CE 3103WLV	Epoxy electrically conductive adhesive	 Pb-free alternative to solder Low-temperature cure Stable contact resistance 	0.0008	114	45	225	4,500	10 min. at 120°C
LOCTITE ABLESTIK ICP 3535M1	Epoxy electrically conductive adhesive	 One component, Pb-free alternative to solder, Sn Compatible Low-temperature cure Stable contact resistance 	0.004	102	36	141	2.6	1 hr. at 150°C or 10 min. at 175°C
Hybrid								
LOCTITE ABLESTIK CE 8500	Epoxy hybrid electrically conductive adhesive	 One component Low stress Flexible for bonding mismatched adherends 	0.0002	24	55	380	2.5	90 min. at 120°C or 40 min. at 150°C or 15 min. at 175°C
Silicone								
LOCTITE ABLESTIK ICP 4001	Silicone electrically conductive adhesive	 One component High flexibility Excellent electrical conductivity High temperature performance Pb-free alternative to solder Outstanding elongation performance Low outgassing 	4×10 ⁻⁴	-50	N/A	370	101	1 hr. at 130°C

Electrically Conductive Adhesives

Product Name	Description	Key Attributes	Volume Resistivity (Ω∙cm)	Shore A Hardness	Attenuation	Tensile Lap Shear Strength (N/m²)	Recommended Cure
EMI Shielding Silicone							
LOCTITE SI 5421	Silicone electrically conductive adhesive	 Room temperature cure Low stress High flexibility, EMI Shielding gasketing material 	< 1 X 10 ⁻²	50 - 65	80dB at 10 Mhz, 110dB at 100 MHz, 100 dB at 10 GHz	0.7	24 hr. at 25°C

PRINTED INKS

Product Name	Description	Key Attributes	Coverage at 10 µm (m²/kg)	Sheet Resistance (Ω/sq/25 µm)	Processing	Substrates	Recommended Cure
PTC Carbon Inks							
LOCTITE ECI 8120 E&C	Positive temperature coefficient (PTC) printable ink	 Flexible Printable on most common substrates Self-regulating heater with PTC temperature of 120°C 	43	1,700	• Screenprint	 Polyester PEN** Polyimide film PET* 	10 min. at 140°C
LOCTITE ECI 8090 E&C	Positive temperature coefficient (PTC) printable ink	 Flexible Printable on most common substrates Self-regulating heater with PTC temperature of 90°C 	38	1,000	• Screenprint	 Polyester PEN** Polyimide film PET* 	10 min. at 120°C or 140°C
LOCTITE ECI 8001 E&C	Positive temperature coefficient (PTC) printable ink	 Flexible Printable on most common substrates Self-regulating heater with PTC temperature of 65°C 	48	1,700	• Screenprint	 Polyester PEN** Polyimide film PET* 	10 min. at 120°C
Silver Inks							
LOCTITE ECI 1010 E&C	Screen printable, conductive ink	 Flexible Good adhesion High conductivity with optimum mechanical performance Compatible with LOCTITE EDAG 440A E&C, LOCTITE EDAG 440B E&C and LOCTITE EDAG PF 455B E&C 	10.6	0.007	• Screenprint	• Polyimide film • PET*	15 min. at 120°C
LOCTITE EDAG 479SS E&C	Screen printable, very fast drying, conductive ink	 Conductive Fast drying Superior adhesion to polyester film Excellent fine line printing Excellent creasability 	14.6	< 0.02	• Screenprint	 Membrane switches Flexible circuitry display devices 	15 min. at 100°C
LOCTITE EDAG 725A E&C (6S-54)	Screen printable, easy processing, conductive ink	 Conductive Process ease Excellent adhesion Good printability and screen residence time Excellent flexibility 	11	< 0.015	• Screenprint	 PET* Membrane Keyboards Other flexible foils 	15 min. at 120°C
LOCTITE EDAG 976SS HV E&C	Screen printable, thermoset, conductive ink	 Highly conductive Resistant to wave soldering Excellent adhesion Excellent screen residence time Solvent resistant 	18	< 0.025	• Screenprint	Phenolic paper Epoxy paper Glass epoxy Copper laminated substrates plain substrates	Pre-dry 15 min. at 70°C followed by cure of 30 min. at 150 to 160°C
LOCTITE ECI 1011 E&C	Flexography and screen printable conductive ink	 Highly conductive Small particle size Excellent adhesion Excellent printability with flexography Flexible 	8.3	< 0.005	 Screenprint Flexographic Rotogravure 	 Polyester PEN** Polyimide film PET* 	10 min. at 150°C

* Polyethylene Terephthalate ** Polyethylene Naphthalate *** Indium Tin Oxide

SOLDER MATERIALS

Cored Wire

Product Name	Description	Key Attributes	Approximate Flux Content (% by Weight)	Diameter Range (mm)	Pb-Free Alloy	SnPb Alloy	IPC J-STE-004B Classification
Halide-Free, No-Clean							
LOCTITE C 502	Cored solder wire	Clear residueGood wetting on difficult substratesMedium activity flux	2.7	0.25 – 1.63	• 96SC (SAC387) • 97SC (SAC305) • 99C (SnCu)	• Sn60 • Sn62 • Sn63	ROM1
Halogen-Free, No-Clean							
LOCTITE C 400	Cored solder wire	 Clear residue Increased flux content for improved wetting on challenging surfaces Award-winning multiple flux core technology that ensures consistent distribution of flux throughout the solder wire Suitable for manual and robotic soldering 	2.2	0.38 – 1.63	• 90iSC • 99C • SAC305 • SAC387	• Sn60 • Sn62 • Sn63	ROLO

Liquid Flux

Product Name	Description	Key Attributes	Solid Content (% by Weight)	Acid Value (mg KOH/g)	Application	IPC J-STE-004B Classification
Halogen-Free, No-Clean						
LOCTITE MF 390HR	Liquid flux	 Exceptional through-hole fill Recommended for automotive applications and general electrical soldering applications Compatible with Pb-free and SnPb wave solder processes 	6	20 - 25	Spray/Foam	ROLO

Solder Paste

Product Name	Description	Key Attributes	Alloy	Particle Size Distribution	IPC J-STE-004B Classification	Optimal Shelf Life	Reflow Atmosphere
Halogen-Free, No-Clean							
LOCTITE HF 212	No-clean, halogen free, solder paste	 High tack Low voiding RoHS-compliant Excellent fine pitch coalescence Designed for medium to large boards 	• 90iSC • SAC0307 • SAC305 • SAC387	• Type 3 • Type 4 • Type 4.5 (4A) • Type 5	ROLO	6 months at 0 – 10°C	Air and Nitrogen





Amplified Protection

Once reliable assembly is achieved, multiple areas of power storage systems have to be enhanced with protective materials to fortify the battery ecosystem against moisture, corrosion, automotive fluids, vibration and thermal shock. Henkel conformal coatings, encapsulants and potting materials provide this defense for the PCB, isolating and protecting solder joints and sensitive components from harmful conditions. At the heart of the Li-Ion battery, individual battery cells are augmented with pre-treatment functional coatings of the cathode and anode metal, allowing strengthened bonds for improved conductivity. To keep contaminants out of the battery module and/or battery pack, Henkel TECHNOMELT low pressure molding offers a protective and secure alternative to conventional metal or plastic housings, while Henkel sealants provide an impenetrable barrier for pouches, battery pack housings and coolant systems.



CONFORMAL COATINGS

UV + Moisture Cure

Product Name	Description	Key Attributes	Viscosity at 25°C (cP)	Operating Temperature Range (°C)	Recommended Cure	Color	Volume Resistivity (Ω•cm)
LOCTITE SI 5293	Silicone conformal coating	 One component Exhibits positive fluorescence under UV light Repairable Solvent-free Designed for severe temperature environments and high-reliability automotive applications 	400 - 800	-40 - 200	20 – 40 sec. per side at 70 mW/cm² + 72 hr. at 50% RH	Transparent amber to yellow	1×10 ¹⁴
LOCTITE STYCAST UV 7993	Urethane conformal coating	 One component Solvent-free Good moisture resistance Excellent chemical resistance 	120	- 40 - 130	10 sec. at 200 W/in + 100 hr. at 50% RH	Translucent yellow	2.2×10 ¹⁶
LOCTITE STYCAST PC 40-UMF	Urethane Acrylate conformal coating	 Single component VOC free Conforms to IPC-CC-830 requirements 	250	- 40 - 135	10 sec. at 300 – 600 mW/cm²	Clear	3.5×10 ¹⁶

ENCAPSULANTS

Glob Top - Dam and Fill

Product Name	Description	Key Attributes	Viscosity at 25°C	Glass Transition Temperature,	Coefficient of Thermal Expansion (CTE)		Modulus at 25°C	Recommended Cure
			(CP)	Tg (°C)	Below T _g	Above T _g	(MPa)	
Heat Cure								
LOCTITE ECCOBOND E0 1072	Epoxy encapsulant- dam and fill	 High Tg Low extractable ionics High performance Good shelf life Fast curing One component 	80,000	135	43	123	6,700	5 min. at 140 – 150°C
LOCTITE ECCOBOND EN 3838T	Epoxy encapsulant	 One component Fast cure at moderate temperatures Low Tg Low modulus Reworkable Pb-free applications 	6,700	2	57	217	466	8 min. at 130°C
UV + Moisture Cure		-						
LOCTITE ECCOBOND UV 9052	Acrylate adhesive	 One component Withstands exposure to ink Cures in shadowed areas No stringing 	6,400	2	49	248	1,987	UV cure 0.5 – 1 J for 5 – 10 sec. + moisture cure at ambient humidity

FUNCTIONAL COATINGS

Protective Conductive Coatings

Product Name	Description	Key Attributes	Viscosity at 25°C (cP)	Recommended Cure	Color	Sheet resistance (Ohm/sq/25µm)
BONDERITE L-GP EB 012EU	Water based conductive carbon coating	 Protective coating onto battery electrodes One component Water based Excellent adhesion to aluminum and copper Good chemical resistant 	50 – 200	24 hr. at room temperature or 3 – 10 min. at 70 – 90°C	Black	< 30
BONDERITE S-FN 15000	Water based conductive carbon coating	 Protective coating for aluminum electrodes One component Water based thermosetting resin system Superior electrolyte and solvent resistance 	600	1 min. at 110 – 130°C	Black	25

LOW PRESSURE MOLDING

Product Name	Description	Key Attributes	Color	Operating Temperature (°C)	Shore Hardness	Softening Point (°C)		
Increased Hardness								
TECHNMELT PA 641	Moldable	 Ideal for applications where strength and hardness are needed 	Amber	40°C 125°C	92A	175 +/- 5		
TECHNOMELT PA 646	polyamide	 Good adhesion for high-temperature applications 	Black	40 C 125 C		115 17 5		
High-Temperature Resistant								
TECHNOMELT PA 673	Moldable	Good adhesion to a variety of substrates Excellent moisture resistance Excellent environmental resistance Good adhesion for high-temperature applications	Amber		Black	107 (5		
TECHNOMELT PA 678	polyamide		Black	-40 °C - 140 °C		187 +/- 5		
Thermally conductive								
TECHNOMELT TC 50	Moldable polyamide	 Thermally conductive - 0.7 W/mK Great adhesion to a variety of substrates Ideal for application where strength and hardness are needed 	Black	-40 °C – 140 °C	60D	187 +/- 5		



POTTING

Ероху

Product Name	Description	Key Attributes	Color	Viscosity at 25°C (cP) - Part 1/Part 2	Glass Transition Temperature, Tg (°C)	Shore Hardness	Recommended Cure
One Component							
LOCTITE STYCAST EO 1058	Ероху	 Excellent chemical resistance High temperature stability Good adhesion to variety of substrate Low CTE 	Black	50,000	140	90	2 hr. at 140°C
LOCTITE STYCAST EO 7038	Ероху	Good chemical resistanceGood thermal shock resistance	Black	40,000	140	92	2 hr. at 140°C
LOCTITE STYCAST A 316-48	Ероху	 Fast heat cure Heat resistant Exceptional thermal stability Excellent chemical resistance 	Black	50,000	145	86	30 min. at 100°C
LOCTITE ECCOBOND ES 70205	Ероху	 Low CTE Good chemical resistance Good thermal shock resistance Good adhesion ot variety of substrates 	Black	17000	97	90	1 hr. at 120°C
Two Component							
LOCTITE STYCAST 2651-40 W1 CAT9	Ероху	 Low viscosity Ease of use Good adhesion to variety of substrate Room Temperature (RT) or heat cure 	Black	33000 / 95	110	88	24 hr. at RT
LOCTITE STYCAST 2850FT CAT9	Ероху	 Thermally conductive (1W/m.K) Low CTE Excellent chemical resistance Electrically insulating 	Black	250000 / 95	86	96	24 hr. at RT
LOCTITE STYCAST E 2534 FR CAT9	Ероху	 Thermally conductive Flame retardant (UL 94V-0 rating in 6mm thickness) Excellent chemical resistance Halogen Free 	Blue	350000 / 95	76	90	24 hr. at RT

SEALANTS

Silicone

Product Name	Description	Key Attributes	Shore A Hardness	Tensile Strength (MPa)	Self-fixture time	Recommended Cure
LOCTITE SI 5970	1K, moisture cure silicone sealant to form a tough rubber gasket	 1K, Ideal for use where high vibration or flexing occurs Can be used with plastic and painted parts Excellent resistance to automotive engine oils 	44	≥ 1.5	Tack-free after 25 min.	21 days at 23°C
BERGQUIST LIQUI BOND TLB 400 SLT	High performance, two-part, silicone adhesive sealant with an adaptable cure profile	 2K - 1:1 mixing ratio Fast and adaptable cure (RT or elevated temperature) Strong and elastic bond Thixotropic Designed for automated dispensing as FIPG (Form-In-Place Gasket) Full compatibility with Gap Filler Chemical resistance High adhesion and elongation Room temperature storage 	40	2.1	12 hr. at 25°C	7 days at 25°C



Running Cool

New Li-Ion batteries now have power and energy densities that are unprecedented, making thorough thermal management of these high-voltage systems non-negotiable for proper operation. If any of the parts overheat – especially those that are flammable – battery work life and, more critically, safety are at risk. As the world's top thermal management materials innovator, Henkel is partnering with today's leading automotive companies to deliver flexible and effective heat management solutions for dependable Li-Ion battery function. Thermal management systems are required throughout the entire Li-Ion battery structure – in between the cells, from the battery to module housing and the module to battery pack housing. Henkel's thermal interface materials – in liquid and pad format – permeate the Li-Ion battery system, providing insulation for safe in-use functionality, and contributing to the reliability of road-ready electric and plug-in hybrid electric vehicles.



THERMAL CLAD INSULATED METAL SUBSTRATES (IMS)

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Thickness (µm)	Dielectric Strength (VAC/mil)	Flammability Rating	Dielectric Constant
Coatings							
BERGQUIST ISOEDGE PR4305	Thermally conductive, electrically isolating powder coat	 Low thermal impedance Good thermal conductivity Good dielectric strength UL certified Eliminates need for thick gap fillers 	0.6	100 - 250	650	UL 94V-0	6
IMS Circuits							
BERGQUIST TCLAD HT DIELECTRIC	Thermally conductive, electrically isolating dielectric	 Very low thermal impedance High thermal conductivity Great dielectric strength UL certified Eutectic AuSn compatible 	2.2	76	2,000	UL 94V-0	7

THERMAL INTERFACE MATERIALS

Gap Filler

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Viscosity at 25°C (cP)	Dielectric Strength (V/25 µm)	Flammability Rating	Recommended Cure
BERGQUIST GAP FILLER 1000SR	Two-part, thermally conductive, and slump resistant liquid gap filling material	 Excellent slump resistance (stays in place) Ultra-conforming, with excellent wetout for low stress interface applications 100% Solids - no cure by-products Excellent low and high temperature mechanical and chemical stability 	1	20 Pa-S (ASTM D5099)	500	UL 94V-0	20 min. at 25°C
BERGQUIST GAP FILLER 1450	Two-part, thermally conductive, liquid gap filling material	 Ultra-conforming with excellent wet- out for near zero interface stress No cure by-products Low density for weight sensitive application Excellent low and high temperature mechanical and chemical stability Shear thinning viscosity for ease of dispensing 	1.5	Part A: 30 Pa-S (ASTM D5099) Part B: 200 Pa-S (ASTM D2196)	275	UL 94V-0	5 hr. at 25°C
BERGQUIST GAP FILLER 1500 LV	Thermally conductive liquid gap filling material	 Low volatility for silicone sensitive applications Ultra-conforming, with excellent wet-out 100% solids — no cure by-products Excellent low and high temperature, chemical and mechanical stability Ambient or accelerated cure schedules 	1.8	20,000	400	UL 94V-0	8 hr. at 25°C
BERGQUIST GAP FILLER 3500LV	Thermally conductive, low outgassing, liquid gap filling material	 Low volatility for outgassing sensitive applications Ultra-conforming with excellent wet-out for low stress interfaces on applications 100% solids - no cure by-products Ambient or accelerated cure schedules 	3.5	45,000	275	UL 94V-0	24 hr. at 25°C

GAP PAD

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Modulus at 25°C (KPa)	Dielectric Breakdown Voltage	Thickness (mm)	Flammability Rating
BERGQUIST GAP PAD HC3.0	High-compliance, thermally conductive, low modulus, gap filling material	 High-compliance, low compression stress Fiberglass reinforced for shear and tear resistance 	3	110	5,000 V (at 500 µm)	• 0.508 – 3.175	UL 94V-0
BERGQUIST GAP PAD HC5.0	High-compliance, thermally conductive, low modulus, gap filling materiall	 Exceptional thermal performance High-compliance, low compression stress Fiberglass reinforced for shear and tear resistance 	5	121	5,000 V (at 500 µm)	 0.508 1.016 1.524 2.032 2.540 3.175 	UL 94V-0
BERGQUIST GAP PAD 1450	Highly compliant gap pad material	 Permanent liner reinforcement allows easy rework and resistance to puncture and tear resistance Highly conformable/low hardness Designed for and low-stress applications 	1.3	110	6,000 V (at 500 µm)	• 0.508 – 3.175	UL 94V-0
BERGQUIST GAP PAD 1000HD	High durability gap pad	 Robust Polymide carrier provides excellent voltage breakdown, puncture and tear resistance Highly conformable Ease of handling and rework in applications 	1	414	10,000 V (at 500 μm)	• 0.508 - 3.175	UL 94V-0
BERGQUIST GAP PAD 2200SF	Thermally conductive, silicone-free gap filling material	 Medium compliance with easy handling Electrically isolating 	2	228	5,000 V (at 250 µm)	• 0.254 - 3.175	UL 94V-0



Phase Change Materials

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Phase Change Temperature (°C)	Dielectric Breakdown Voltage	Dielectric Breakdown Voltage	Flammability Rating
Polymide Carrier							
BERGQUIST HI-FLOW 300P	Electrically insulating, thermally conductive phase change material	 Field-proven polyimide film Excellent dielectric performance Excellent cut-through resistance Outstanding thermal performance in an insulated pad 	1.6	55	5000 V	0.025 - 0.050	94V-0
BERGQUIST HI-FLOW 650P	Electrically insulating, thermally conductive phase change material	 Thermal impedance: 0.20°C-in²/W (at 25 psi) 150°C high temperature reliability Natural tack one side for ease of assembly Exceptional thermal performance in an insulated pad 	1.5	52	5000 V	0.025 - 0.050	UL 94V-0
No Carrier							
BERGQUIST HI-FLOW 565UT	Tacky, high performance, un-reinforced phase change material	 Very low thermal impedance High thermal conductivity Natually tacky Used for applications that do not require electrical insulation Tabulated for ease of assembly 	3	52	N/A	0.127 - 0.254	UL 94V-0

SIL PAD

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Hardness	Dielectric Breakdown Voltage	Thickness (mm)	Flammability Rating
Polymide Carrier							
BERGQUIST SIL-PAD A2000	A conformable thermally conductive elastomer	 Thermal impedance: 0.32°C-in²/W (at 50 psi) Optimal heat transfer 	3	90 (Shore A)	4000 V	0.381 to 0.508	UL 94 V-0
BERGQUIST SIL-PAD 900S	Thermally conductive and electrical insulation material	 Thermal impedance: 0.61°C-in²/W (at 50 psi) Electrically isolating Low mounting pressures Smooth and highly compliant surface General-purpose thermal interface material solution 	1.6	92 (Shore 00)	5500 V	0.229	UL 94 VTM-0
No Carrier							
BERGQUIST SIL-PAD K-10	A high performance insulator to replace ceramic insulators such as Beryllium Oxide, Boron Nitride, and Alumina	 Thermal impedance: 0.41°C-in²/W (at 50 psi) Tough dielectric barrier against cut- through High performance film Designed to replace ceramic insulators 	1.3	90 (Shore 00)	6000 V	0.152	UL 94 VTM-O

Thermal Adhesives

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Thickness	Dielectric Strength	Flammability Rating	Lap Shear at RT
Tapes							
BERGQUIST BOND-PLY 800	Thermally conductive, electrically isolation double-sided tape	 Thermal impedance: 0.60°C-in2/W (at 50 psi) High bond strength to most epoxies and metals Double-sided, pressure sensitive adhesive tape High performance, thermally conductive acrylic adhesive More cost-effective than heat-cure adhesive, screw mounting or clip mounting 	0.8	• 0.127mm • 0.203mm	4000 V	UL 94 V-0	150 Psi
BERGQUIST BOND-PLY LMS-HD	Thermally conductive heat curable laminate material	 TO-220 Thermal performances: 2.3°C/W, initial pressure only lamination Exceptional dielectric strength Very low interfacial resistance Continuous use of -60 to 180°C Eliminates mechanical fasteners 	1.4	• 0.254mm • 0.457mm	4000 V	UL 94 V-0	200 Psi

Thermal Adhesives - Continued

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Viscosity	Dielectric Strength	Flammability Rating	Recommended Cure
Liquids							
BERGQUIST LIQUI BOND TLB SA 1800	High performance, liquid silicone adhesive	 Eliminates need for mechanical fasteners Low viscosity for ease of screening or stenciling Maintains structural bond in severe- environment applications Heat cure 	1.8	125,000 cps	250 V/mil	UL 94 V-0	20 min. at 125°C or 10 min. at 150°C
BERGQUIST LIQUI BOND TLB SA2005RT	Two-part, high performance silicone thermal adhesive	 Adaptive thermal cure No cure by-products Cures and bonds at room temperature Cure rate is greatly accelerated at elevated temperatures Room temperature storage 	2	Part A: 70 Pa-S Part B 70 Pa-S	275 V/mil	UL 94 V-0	7 days at 25°C or 1 hr. at 85°C

LOCTITE. TECHNOMELT.



AMERICAS

HEADQUARTERS: UNITED STATES

Henkel Corporation 14000 Jamboree Road Irvine, CA 92606 USA Tel: +1.888.943.6535 Fax: +1.714.368.2265

Henkel Corporation 20021 Susana Road Rancho Dominguez, CA 90221 USA Tel: +1.310.764.4600 Fax: +1.310.605.2274

Henkel Corporation 18930 W. 78th Street Chanhassen, MN 55317 USA Tel: +1.952.835.2322 Tel: +1.800.347.4572 Fax: +1.952.835.0430

BRAZIL

Henkel Brazil Av. Prof. Vernon Krieble, 91 06690-070 Itapevi, Sao Paulo, Brazil Tel: +55.11.3205.7001 Fax: +55.11.3205.7100

ASIA-PACIFIC

CHINA

No. 332 Meigui South Road WaiGaoQiao Free Trade Zone, Pu Dong Shanghai 200131, P.R. China Tel: +86.21.3898.4800 Fax: +86.21.5048.4169

JAPAN

Henkel Japan Ltd. 27-7, Shin Isogo-cho Isogo-ku Yokohama, 235-0017 Japan Tel: +81.45.286.0161 Email: jp.ae-csdesk@henkel.com

KOREA

Henkel Korea Co.,Ltd 18th floor of tower B, BYC High City Bldg Gasan Digital 1-ro, Geumcheon-gu, Seoul, 08506, South Korea Tel : +82.2.6150.3000 Fax: +82.2.6947.5203

SINGAPORE

Henkel Singapore Pte Ltd. 401, Commonwealth Drive #03-01/02 Haw Par Technocentre, Singapore 149598 Tel: +65.6266.0100 Fax: +65.6472.8738 / +65.6266.1161

EUROPE

BELGIUM

Henkel Electronics Materials (Belgium) N.V. Nijverheidsstraat 7 B-2260 Westerlo Belgium Tel: +32.1457.5611 Fax: +32.1458.5530

UNITED KINGDOM

Henkel Ltd. Adhesives Limited Technologies House Wood Lane End Hemel Hempstead Hertfordshire HP2 4RQ Tel: +44.1442.278000 Fax: +44.1442.278071



henkel-adhesives.com/electronics henkel-adhesives.com/thermal